IPC ASSOCIATION ELECTRONIC	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved unde international and Pan-American copyright conventions.		This docum level parts,						ted item. Note: if he manufacturer				
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier	r Information													
Company name* Company unique ID			ique ID		Unique ID Authority				Res	Response Date*				
nsemi										2024	2024-04-25			
Contact N	ame		Title - Contact			Phone - Contact*				Ema	Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative			Phone - Representative*			Ema	Email - Representative*				
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	Requester Item Number Mfr Item		n Number	fumber Mfr Item Name		Effective Date	e Versio	on	Manufacturing Site		Weight*	UOM	Unit Type	
		NFAM3065L4BTL SPM31, 650V/30A		A Inverter IPM, Low noise	2024-04-25			VN5		8944.253	mg	Each		
	cturing Process Inform		Comminal Dago	Allow	-STD-020 MSL Rating	Dools Duo	aasa Dadu	Tommonoto	May Time a	t Dool: Tome	Number	of Doflary Cy	olog	
	3		erminal Base Alloy J-STD-020 MSL Rate VAlloy NA			Peak Process Body Temperature Max Time at		Γ.	seconds Number of Reflow Cycles Seconds 3		cies			
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RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	461.068	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		184.4272	mg
			Supplier	Copper (Cu)	7440-50-8		276.6408	mg
Die	51.5022	mg	Supplier	Silicon (Si)	7440-21-3		51.5022	mg
Die Attach	1.41124	mg		Epoxy resin	proprietary data		0.2173	mg
			Supplier	Imidazole Addition	68490-66-4		0.0226	mg
			Supplier	Silver (Ag)	7440-22-4		1.0867	mg
			В	Bismuth Trioxide (Bi2O3)	1304-76-3		0.0607	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.024	mg
Die Attach Solder	4.19991	mg	Supplier	Silver (Ag)	7440-22-4		0.105	mg
			Supplier	Tin (Sn)	7440-31-5		4.0739	mg
			Supplier	Copper (Cu)	7440-50-8		0.021	mg
Lead Frame	462.339	mg	Supplier	Silver (Ag)	7440-22-4		23.1169	mg
			Supplier	Zinc (Zn)	7440-66-6		0.5548	mg
			Supplier	Iron (Fe)	7439-89-6		11.0961	mg
			Supplier	Copper (Cu)	7440-50-8		427.2012	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3699	mg
Mold Compound-Black	7922.92	mg	Supplier	Carbon Black (C)	1333-86-4		79.2292	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6734.4819	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1109.2087	mg
NTC	4.6965	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.2001	mg
			Supplier	Silver (Ag)	7440-22-4		0.047	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0122	mg
			Supplier	Tin (Sn)	7440-31-5		0.078	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		0.9999	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0348	mg
			Supplier	Palladium (Pd)	7440-05-3		0.1099	mg
			Supplier	Iron Trioxide (Fe2O3)	1309-37-1		0.2001	mg
			В	Nickel (Ni)	7440-02-0		0.0333	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		2.6	mg
			Supplier	Copper (Cu)	7440-50-8		0.3814	mg
Plating	0.16692	mg	Supplier	Tin (Sn)	7440-31-5		0.1669	mg
Solder Wire	7.24278	mg	A	Lead (Pb)	7439-92-1	7a	6.8806	mg

			Supplier	Tin (Sn)	7440-31-5	0.3621	mg
Wire Bond - Al	28.5763	mg	Supplier	Aluminum (Al)	7429-90-5	28.5763	mg
Wire Bond - Cu	0.1304	mg	Supplier	Copper (Cu)	7440-50-8	0.1304	mg